



8711

제품 정보

30µm translucent-white low temperature reactive HAF mounting tape

제품 설명

tesa® Low Temperature Reactive (LTR) 8711 is a reactive mounting tape activated at moderate temperatures. It is protected by a PE-coated paper liner.

It is activated by moderate heat and pressure applied during the assembly process.

특성

- Extremely strong bonding
- Excellent reliability after curing, even in hot climate
- Sebum resistant
- Very low oozing ratio
- Activated at low temperature and pressure
- At room temperature tesa® LTR 8711 is not tacky.
- This translucent-white double-sided tape has no backing.
- tesa® LTR 8711 is free of halogen and compliant with current RoHS directive.

Applications

tesa® LTR 8711 is especially recommended for reliable bonding of temperature sensitive materials in consumer electronics devices and accessories:

- Bonding of fabrics and leather
- Bonding of plastics
- Bonding of sensitive electronic parts

Technical Information (average values)

The values in this section should be considered representative or typical only and should not be used for specification purposes.

제품 구조

- | | | | |
|----------|---------------|-------|-------|
| • 기재 소재 | 없음 | • 총두께 | 30 µm |
| • 점착제 종류 | 저온 활성화 반응 점착제 | • 컬러 | 반투명 |
| • 이형지 종류 | PE 코팅된 직물 | | |

속성 / 성능 값

- | | | | |
|----------|-----------|---------------|-----------------------|
| • 낮은 VOC | very good | • 점착력 (푸쉬 아웃) | 5.5 N/mm ² |
|----------|-----------|---------------|-----------------------|

관련제품 최신자료는 다음의 경로를 클릭하세요 <http://l.tesa.com/?ip=08711>



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추가정보

Technical recommendations:

tesa® LTR 8711 is not self adhesive. It is activated by heat and pressure over a certain interval. The following values are recommendations for bond line parameters to start with.

1. Pre-lamination:

During pre-lamination, laminate the adhesive tape onto the first component.

Setting:

- Temperature¹ 50 – 60 °C
- Pressure² 1 – 3 bar
- Time 5 – 20 s

Short-time exposure to 60°C bond line temperature during pre-lamination does not impact final bonding potential.

2. Bonding:

Remove the liner from tape after the pre-lamination step.

Position the second component. Apply temperature and pressure for the bonding time to reach sufficient bonding strength.

Setting:

- Temperature¹ 75 – 110 °C
- Pressure² 2 – 4 bar
- Time 10 – 480 s

Short cycle times can be achieved at 110 °C bond line temperature. For activation at lower temperatures, increase the heat-press time or combine a short heat-press step with oven curing.

To reach maximum bonding strength, surfaces should be clean and dry. Allow at least 1-2 hours dwell-time after bonding before performance testing. Final bonding strength will be reached after 24 hours.

Bonding strength values were obtained under standard laboratory conditions (Material: PC/PC; bonding conditions: temperature (jig) = 90 °C; pressure = 5 bar; time = 120 sec).

Storage:

tesa recommends storage in original packaging in cool and dry conditions.

Low Temperature Reactive should not be exposed to more than 35°C before bonding (during transport, storage and converting).

The shelf life is 15 months after coating date. For the actual shelf life please refer to the best before date on the label in the log roll core.

¹ 'Pre-lamination' and 'Bonding' temperature refer to the data that is measured in the bond line.

² 'Pre-lamination' and 'Bonding' pressure refer to the force that is transferred from jig surface directly to the bonding area.



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